

Components, Packaging, and Manufacturing



IEEE

Technology Society

Newsletter



The Global Society for Microelectronics Systems Packaging



Vol. 30 No. 2, June 2007 (ISSN 1077-2999)

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President's Column.....



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Greetings!!!

ECTC 2007

ECTC 2007 in Reno Nevada came and went very fast. For me personally it started with the 2007 ITRS Assembly and Packaging Working Group meeting on Tuesday morning May 28th, (the same day as the PDC courses and Tin Whisker Workshop). The week ended with the CPMT Board of Governors Meeting on Saturday June 2nd. Of the three exciting ECTC days in between, there were the Technical Committee meetings starting bright and early at 7:00 am (and one Transactions editors meeting at 6:30 am), and three Panel Sessions ending around 9:30 pm and 10:00 pm. In between were the parallel technical paper sessions, poster sessions, technical exhibits, and more committee meetings. The coffee breaks, lunches and dinners provided great opportunities to meet people and exchange gossip. I saw friends and colleagues from all over the globe. For me ECTC has always been a celebration, a celebration that unites people from diverse disciplines and geographies to share their discoveries, knowledge and data, triumphs great and small with their peers from all over the world.

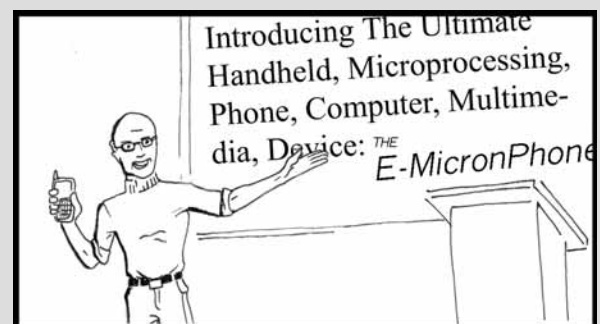
Unscientific Survey

I took an unscientific and incomplete survey. I asked some ECTC attendees for their comments on the technical programs. Almost to a man (or woman) they said that the technical program was outstanding. There were the complaints that parallel sessions made it perplexing as to which paper and what session to attend. They particularly liked the three evening panel sessions. (For the sake of full disclosure, I chaired one of the sessions.) For me the top prize must go to Technical Committee - HDSB for their 3D Packaging Panel held between 8:00 pm to 10:00 pm drawing a room full capacity crowd. The comments on the quality, relevancy, and timeliness of the technical papers were unequivocal. My thanks go to Eric Perfecto, Rao Bonda, and their technical program committees for their tireless efforts and dedication.

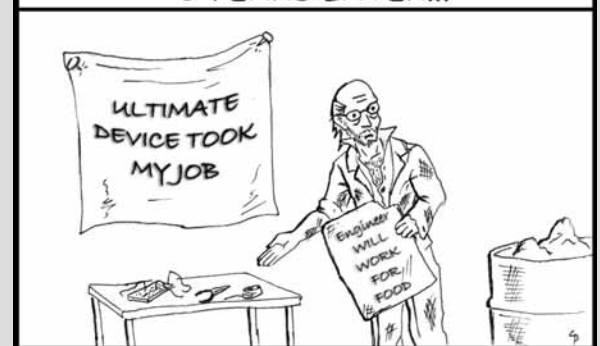
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Cartoon of the Month:

Fine Line between Product Success and Failure



5 YEARS LATER...



... By Dave Palmer

IEEE CPMT Society Newsletter

June, 2007

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Awards & Recognition

A highlight of ECTC has always been the CPMT lunch where IEEE and CPMT recognized exceptional individuals in our midst for their major and significant contributions to our profession and our society. I had the honor to present the IEEE CPMT Field Award to Dimitry Grabbe for his many contributions to advanced printed circuit board technology and connector technology in a professional career of over a half century. I was also privileged to share the podium with Dr Kitty Pearsall, CPMT Strategic Director for Awards and Recognition, to present this year's CPMT Society Awards for contributions and achievements. The list of award recipients and corresponding citations appear elsewhere in this newsletter. Last but not least, we recognized those members in our midst who have attained the highest membership level as an IEEE Fellow this year. The award winners and Fellows comprise a group of extraordinary professionals. Each in his/her own way has contributed much to our profession. And it is important that we recognize our own in major CPMT conferences, including ECTC, EPTC, ESTC, EMAP, IEMT and many others.

Winds of Change

If one should ask me, what were the over-riding impressions that I carry with from ECTC 2007, I would say they are the accelerating pace of technology change, and perhaps equally important, an expanding mindset welcoming change among the participants. The winds of change are gale winds blowing strong.

The traditional perspective of the roles of the packaging engineer is (a) make electrical interconnects and maintain off-chip signal integrity, (b) keep the IC and package temperature in check, (c) keep the IC and package from breaking down over its service life. Moore's Law drives the industry front-end for timed invention, innovation and their implementation. With the waves of SiP, wafer level packaging and 3D packaging technologies coming to the front, the roles of packaging engineers are taking on new dimensions. On the one hand the advancements of WLP and TSV are breaking down the walls between the foundry and packaging. On the other hand the forces unleashed by SiP technologies lead directly to system integration and electronic product realization. In this world of electronics industry the walls between the supply chains are fast vanishing. Are we ready for the challenges and opportunities presented by the advancing and sometimes disruptive technologies and evolving industry business model.

A Safe Harbor

In this fast-changing world of shifting opportunities, the global IEEE/CPMT community is becoming a safe harbor for relevant knowledge, technology innovations, life-long education, global networking, and peer recognition. I would like to invite you to participate in other CPMT conferences and workshops in different regions world-wide. There is still time for abstract submissions and technical exhibitions. They are great opportunities for technical vitality and building your personal networking within those regions. At the Board of Governors workshop last week we asked the Regional Strategic Directors to co-ordinate participation from

publications, technical committees and membership at CPMT related conferences and workshops. I am confident that they will be working enthusiastically towards those ends.

Do go to the CPMT Web Page to see which technical conferences are of professional interest. Check out the Transactions for the latest developments in your field. Volunteer to be a speaker at your local chapter meeting. The Transactions editors would welcome your contributions as authors and reviewers. Tell your colleagues about CPMT and invite them to join.

A vital global CPMT Society is of benefit to everyone, especially today.

CPMT Society News:

IEEE Components, Packaging and Manufacturing Technology Society Board of Governors Meeting June 1st – 2nd, 2007 Reno, Nevada, USA

Report

Submitted by Ms. Marsha Tickman, Executive Director, IEEE CPMT Society

The IEEE CPMT Society Board of Governors held its first meeting of 2007 on 1st and 2nd June 2007 in Reno, Nevada, USA, following the 57th ECTC.

The meeting began on Friday evening, 1 June 2007, with the third in a series of workshops allowing for informal discussion on strategic issues. This workshop continued discussion on creating global communities to serve members of our profession – and methods and strategies to achieve this. Topics included: defining the CPMT Society value propositions, breaking down silos within Society activities and building linkages, creating/utilizing a Regional organization.

On Saturday 2 June 2007, the Board of Governors meeting was called to order at 8:30 am. The following actions were taken:

- Approved minutes of the November 2006 Board of Governors meeting.
- Ratified actions approved via e-mail ballot between the November 2006 and current Board of Governors meetings.
- Approved employing additional staff to support the Transactions Editors and improve review process cycle time.
- Approved change in cosponsorship for the International Electronics Manufacturing Technology Symposium (IEMT): 50% CPMT Santa Clara Valley Chapter; 50% CPMT Society.
- Approved change in cosponsorship for the Organic Microelectronics Workshop: 25 % American Chemical Society, 25% Materials Research Society, 25% American Physical Society, 12.5% Solid-State Circuits Society (IEEE), 12.5% CPMT.
- Approved change in cosponsorship for the International Symposium on Advanced Packaging Materials: Processes, Properties and Interfaces (APM'07): 50% CPMT Santa Clara Valley Chapter; 50% CPMT Society.
- Approved new 100% Sponsorship of the International Workshop on Advances in Sensors and Interfaces (IWASI).
- Approved new Technical Cosponsorship w/fee of the 2007 Workshop on 3D Integration.